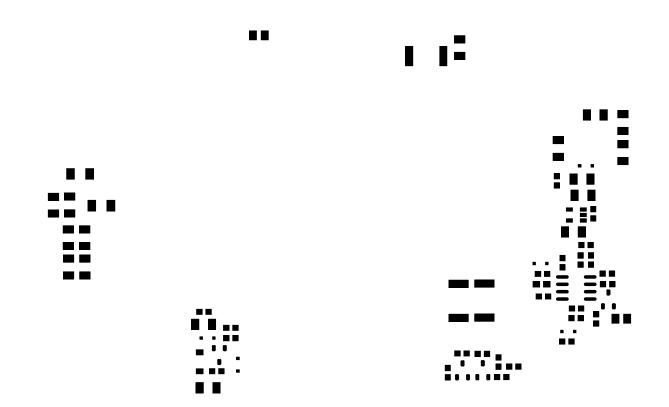
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00443	REV: E2	SVN REV: No	t In VersionControl
LAYER NAME = Top Paste				
PLOT NAME = TIDA-00443-RevB.GTP	GENERATED : 6/1/20	15 <b>4:</b> 31: 21	PM	TEXAS INSTRUMENTS



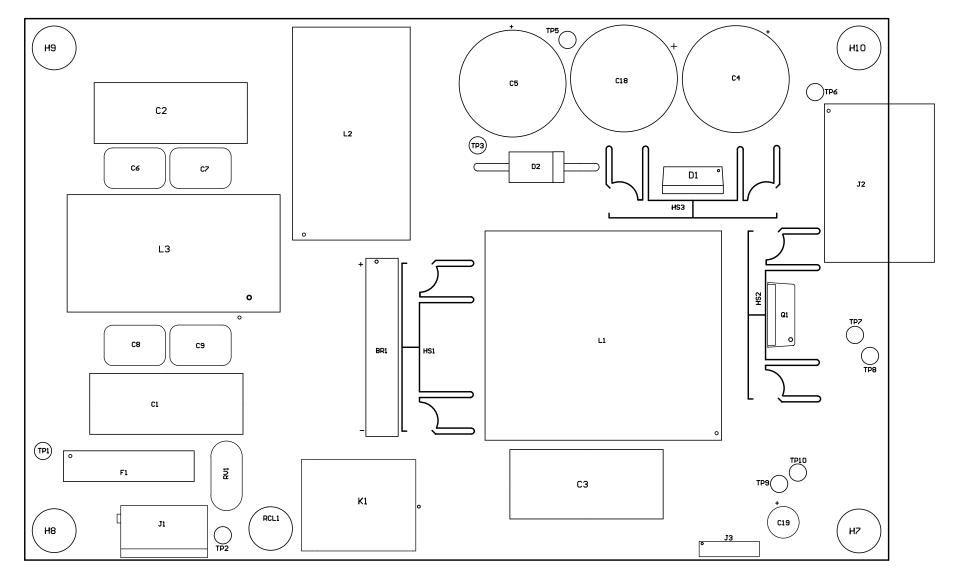


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00443	REV: E2	SVN REV:	Not In VersionControl
LAYER NAME = Bottom Paste				
PLOT NAME = TIDA-00443-RevB.GBP	GENERATED : 6/1/20	<b>4:</b> 31: 21	PM	TEXAS INSTRUMENTS

ZZ4 These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

223 These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

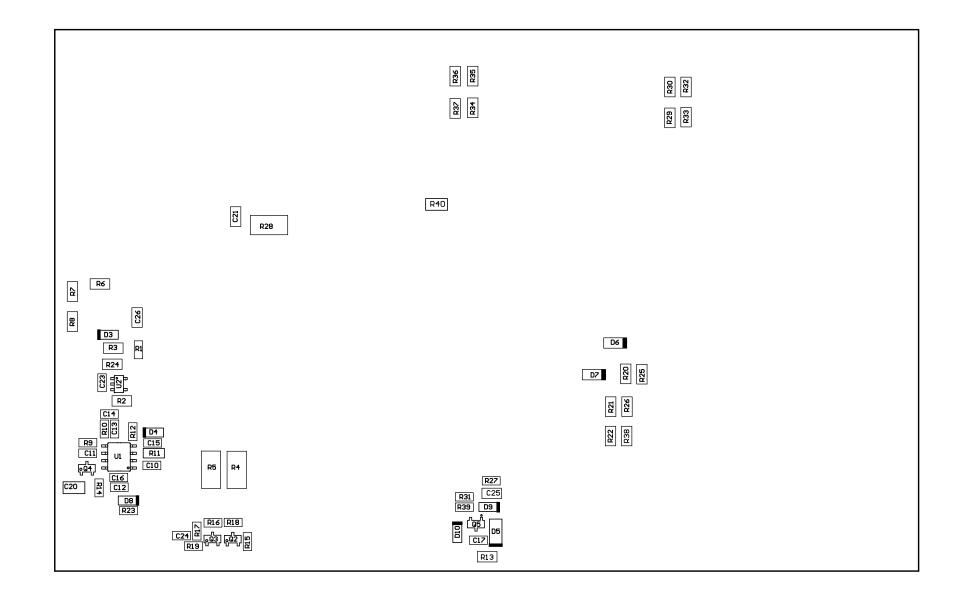
- ZZ2 These assemblies are ESD sensitive, ESD precautions shall be observed.
- ZZI Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.



## COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE		BOARD #:	TIDA-00443		REV: E2	2	SUN REU:	Not In VersionControl
	M5 Assembly Top							
PLOT NAME =	TIDA-00443-RevB. 6M5	GENERATED	: 6	/1/2015	5:11:0	03 PM		TEXAS INSTRUMENTS



## COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: [No Variations]

PGB UIEJED FROM BOTTOM SIDE
BOARD #:
TIDA-00443
REU:
E2
SUN REU:
Not In VersionControl

M66 Assembly Bottom

<

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00443	REV: E2	SUN REU	: Not In VersionControl
LAYER NAME = M1 Board Outline				
PLOT NAME = TIDA-00443-RevB.GM1	GENERATED : 6/1/20	<b>4:</b> 31: 22	PM	TEXAS INSTRUMENTS

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